

*Sub C*

1. (Twice Amended) A printed circuit board unit comprising:

a printed circuit board;

an electronic component;

a solder bump interposed between the printed circuit board and the electronic component so as to fix the electronic component to the printed circuit board; and

an insulated film disposed between the printed circuit board, not adhered thereto, and the electronic component so as to define a through hole for receiving the solder bump, wherein the through hole is designed to form a constriction in the solder bump between the printed circuit board and the electronic component.

*Sub C*

8. (Amended) The printed circuit board unit according to claim 1, wherein an inner surface of the through hole is covered with a coating wet to the solder bump.